

QT-Brightek Optocoupler Series

10Mbit/s High Speed Logic Gate Optocoupler

Part No.: 6N137, QT2601



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Introduction

Feature:

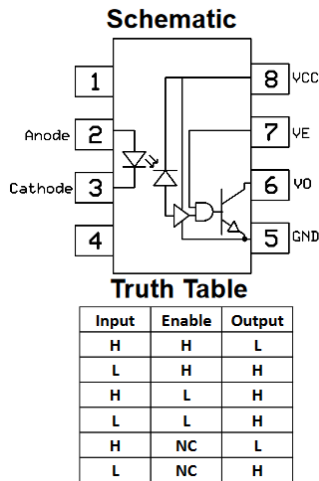
- High Speed 10Mbit/s
- High Isolation voltage between input and output (Viso = 5000V rms)
- Creepage distance > 7.4mm
- Available in Tube or Tape and reel
- Available with standard DIP-8, Gullwing lead bend, SMD lead bend, and SMD low profile options.

Certification & Compliance:

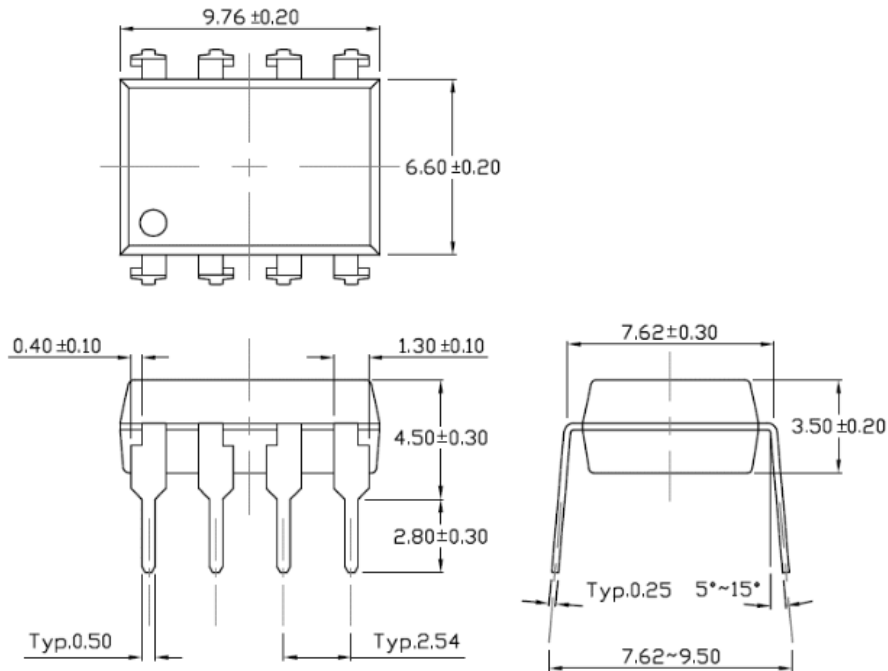
- Pb free and RoHS Compliant
- UL recognized (File #E338132)
- VDE (File #40030457)



Schematic:

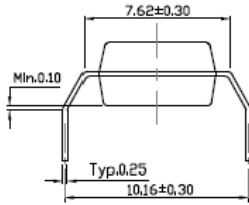


Package Dimension

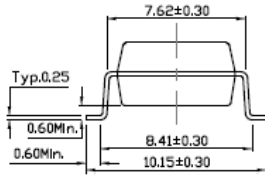


Forming Option

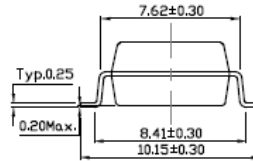
M Type



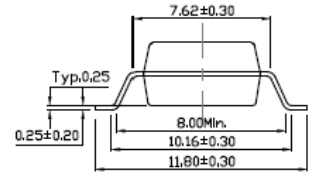
S Type



SL Type



SLM Type



Unit: mm

Absolute Maximum Rating

Symbol	Parameter	Rating	Units
V_{ISO}	Isolation Voltage*	5000	V_{RMS}
T_{STG}	Storage Temperature	-55 ~ +125	°C
T_{OPR}	Operating Temperature	-55 ~ +100	°C
T_{SOL}	Lead Solder Temperature	260 for 10 sec	°C
EMITTER			
I_F	Forward Current	50	mA
V_R	Reverse Voltage	5	V
P_I	Power Dissipation	100	mW
DETECTOR			
P_O	Power Dissipation	85	mW
I_O	Average Output current	50	mA
V_O	Output voltage**	3.0 ~ 7.0	V
V_{CC}	Supply voltage	3.0 ~ 7.0	V
V_E	Enable Input Voltage Not to Exceed V_{CC} by more than 500mW	5.5	V

Electrical Characteristic

Typical values are measured at $T_A=25^\circ\text{C}$ and $V_{CC}=5\text{V}$

Emitter

Symbol	Characteristics	Test Condition	Range			Unit
			Min	Typ	Max	
V_F	Forward Voltage	$I_F = 10\text{mA}$	-	1.4	1.6	V
V_R	Reverse Voltage	$I_R = 10\mu\text{A}$	5.0	-	-	V
$\Delta V_F / \Delta T_A$	Temperature coefficient of forward voltage	$I_F = 10\text{mA}$	-	-1.8	-	mV/ $^\circ\text{C}$

Detector

Symbol	Characteristic	Test Condition	Range			Unit
			Min	Typ	Max	
I_{CCH}	Logic High Supply Current	$I_F=0\text{mA}, V_E=0.5\text{V}, V_{CC}=3.3\text{V}$	-	4.0	10	mA
		$I_F=0\text{mA}, V_E=0.5\text{V}, V_{CC}=5.5\text{V}$	-	6.5	10	
I_{CCL}	Logic Low Supply Current	$I_F=10\text{mA}, V_E=0.5\text{V}, V_{CC}=3.3\text{V}$	-	5.5	13	mA
		$I_F=10\text{mA}, V_E=0.5\text{V}, V_{CC}=5.5\text{V}$	-	8.8	13	
V_{EH}	High Level Enable Voltage	$I_F=10\text{mA}, V_{CC}=3.3\text{V}$	2.0	-	-	V
		$I_F=10\text{mA}, V_{CC}=5.5\text{V}$	2.0	-	-	
V_{EL}	Low Level Enable Voltage	$I_F=10\text{mA}, V_{CC}=3.3\text{V}$	-	-	0.8	V
		$I_F=10\text{mA}, V_{CC}=5.5\text{V}$	-	-	0.8	
I_{EH}	High Level Enable Current	$V_E=2.0\text{V}, V_{CC}=3.3\text{V}$	-	-0.2	-1.6	mA
		$V_E=2.0\text{V}, V_{CC}=5.5\text{V}$	-	-0.53	-1.6	
I_{EL}	Low Level Enable Current	$V_E=0.5\text{V}, V_{CC}=3.3\text{V}$	-	-0.42	-1.6	mA
		$V_E=0.5\text{V}, V_{CC}=5.5\text{V}$	-	-0.75	-1.6	

Transfer Characteristics

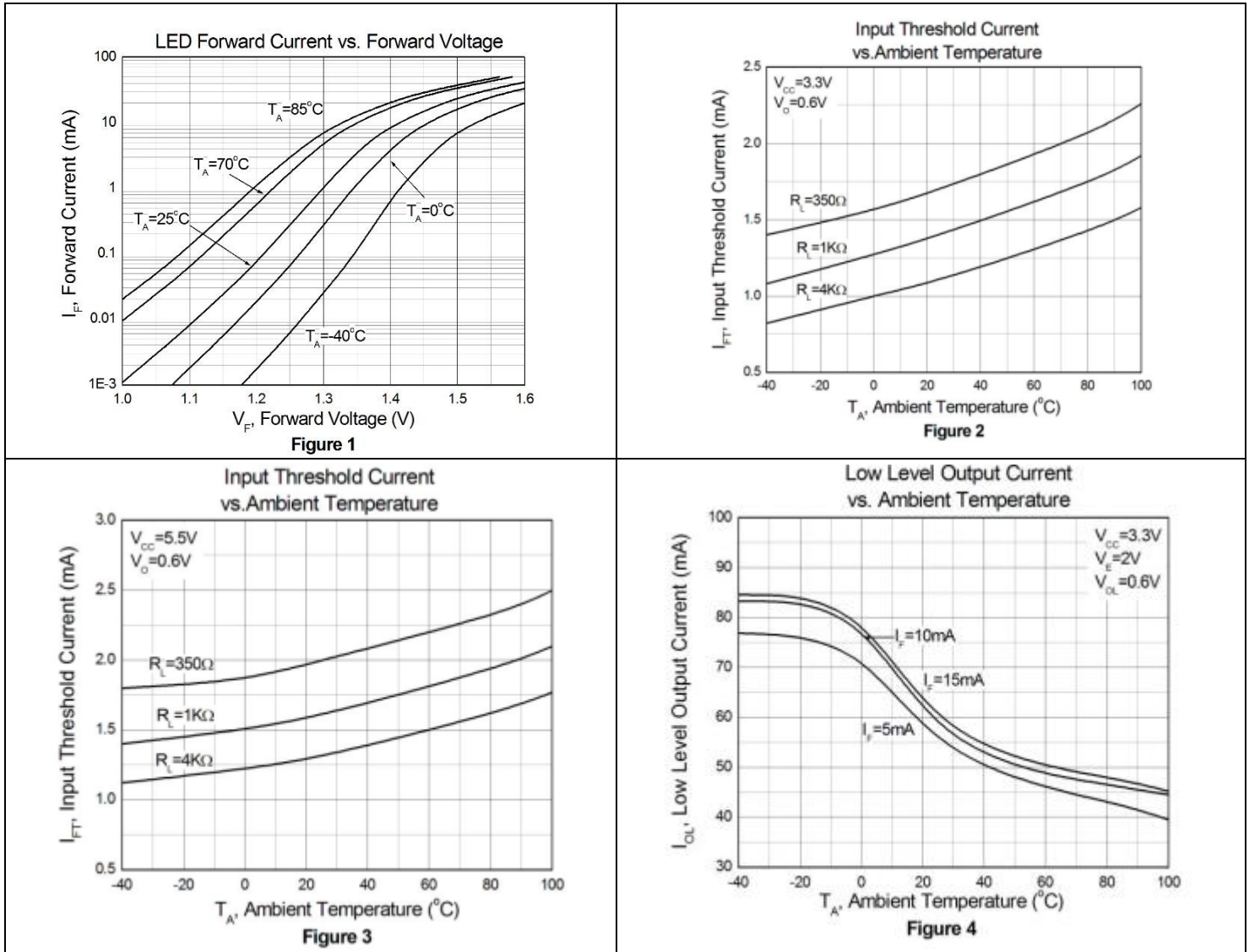
Symbol	Characteristic	Test Condition	Range			Unit
			Min	Typ	Max	
I _{FT}	Input Threshold Current	V _{CC} =3.3V, V _O =0.6V, V _E =2.0V, I _O =13mA	-	1.6	5	mA
		V _{CC} =5.5V, V _O =0.6V, V _E =2.0V, I _O =13mA		2.5	5	
I _{OH}	Logic High Output Current	I _F =250μA, V _O =V _{CC} =3.3V, V _E =2.0V	-	7.0	100	μA
		I _F =250μA, V _O =V _{CC} =5.5V, V _E =2.0V		2.0	100	
V _{OL}	Logic Low Output Voltage	I _F =5mA, I _O =13mA, V _{CC} =3.3V, V _E =2.0V	-	0.45	0.6	V
		I _F =5mA, I _O =13mA, V _{CC} =5.5V, V _E =2.0V		0.35	0.6	

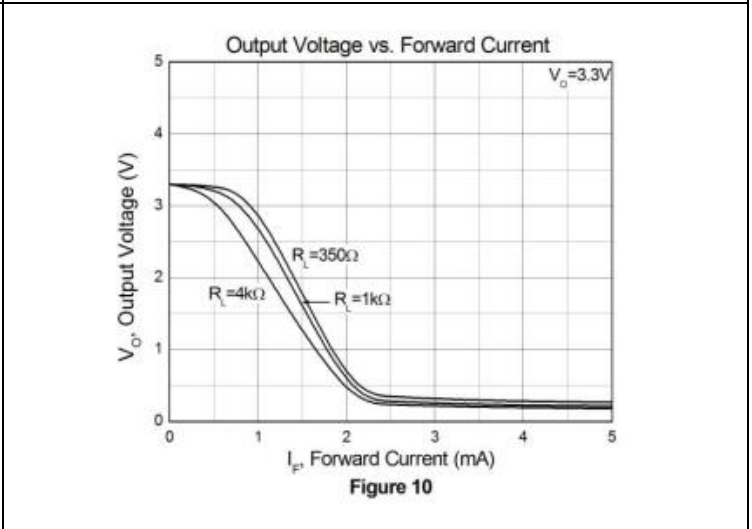
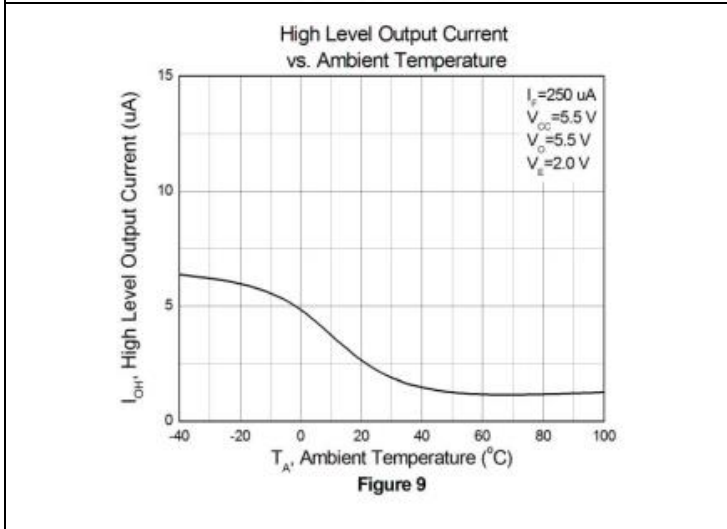
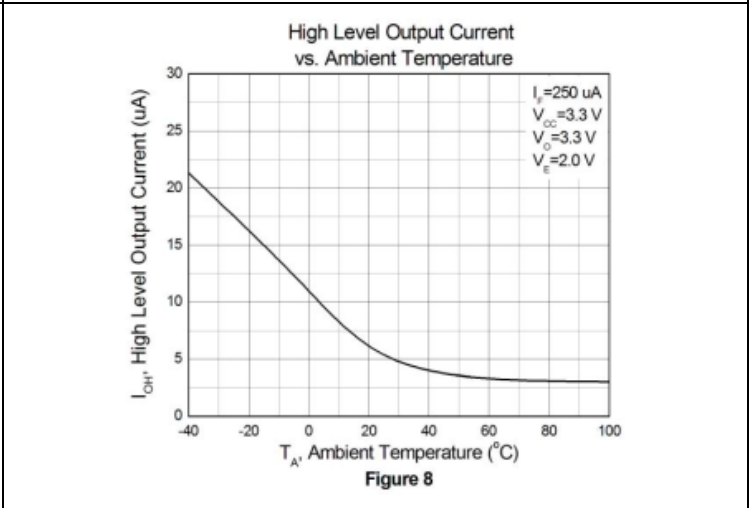
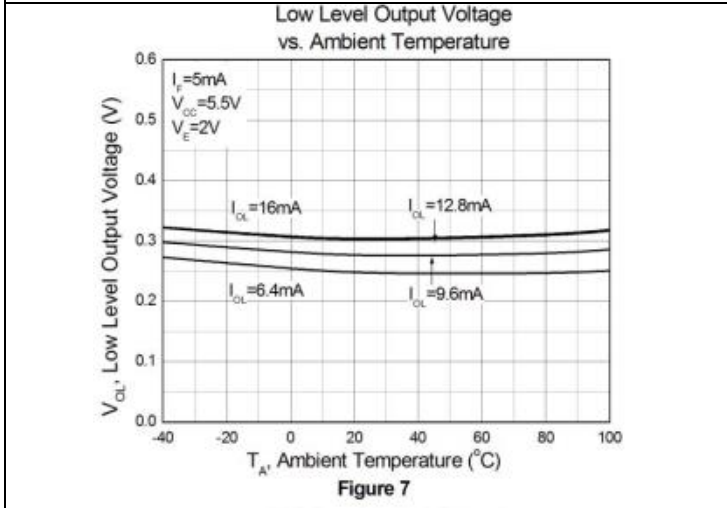
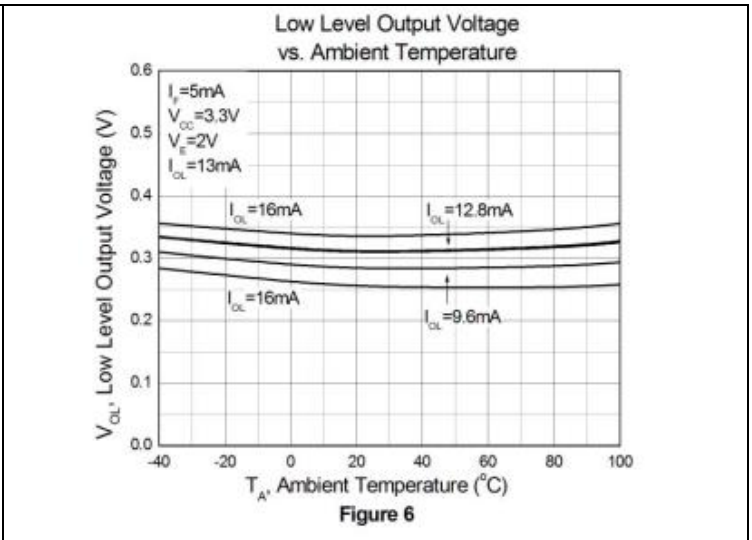
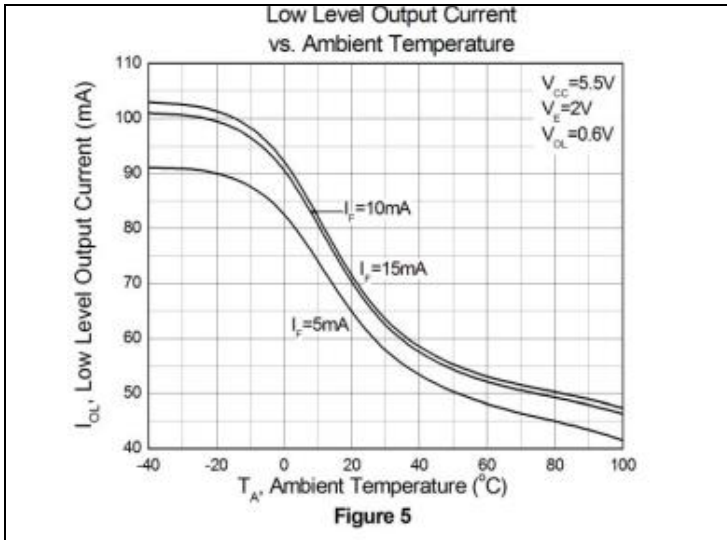
Switching Characteristics (T_A=25°C, V_{CC}=5V)

Symbol	Characteristic	Test Condition	Range			Unit
			Min	Typ	Max	
T _{PHL}	Propagation Delay Time Logic High to Logic Low	C _L = 15pF, R _L = 350Ω V _{CC} =3.3V	-	34	75	ns
		C _L = 15pF, R _L = 350Ω V _{CC} =5.5V				
T _{PLH}	Propagation Delay Time Logic Low to Logic High	C _L = 15pF, R _L = 350Ω V _{CC} =3.3V	-	50	75	
		C _L = 15pF, R _L = 350Ω V _{CC} =5.5V		39	75	
P _{WD}	Pulse Width Distortion	C _L = 15pF, R _L = 350Ω V _{CC} =3.3V	-	16	34	
		C _L = 15pF, R _L = 350Ω V _{CC} =5.5V		5	34	
T _r	Output Rise Time	C _L = 15pF, R _L = 350Ω V _{CC} =3.3V	-	37	-	
		C _L = 15pF, R _L = 350Ω V _{CC} =5.5V				
T _f	Output Fall Time	C _L = 15pF, R _L = 350Ω V _{CC} =3.3V	-	10	-	
		C _L = 15pF, R _L = 350Ω V _{CC} =5.5V				
T _{ELH}	Enable Propagation Delay Low To High	V _{EH} =3.5V, C _L =15pF, R _L =350Ω	-	15	-	ns
T _{EHL}	Enable Propagation Delay High To Low		-	15	-	ns

CM _H	Common Mode Transient Immunity at Logic High	6N137	I _F =0mA, V _{CM} =50Vp-p, V _{OH} =2.0V, R _L =350Ω	-	10000	-	V/μs
		QT2601		5000	10000	-	
CM _L	Common Mode Transient Immunity at Logic Low	6N137	I _F =7.5mA, V _{CM} =50Vp-p, V _{OH} =0.8V, R _L =350Ω	-	10000	-	
		QT2601		5000	10000	-	

Characteristic Curves





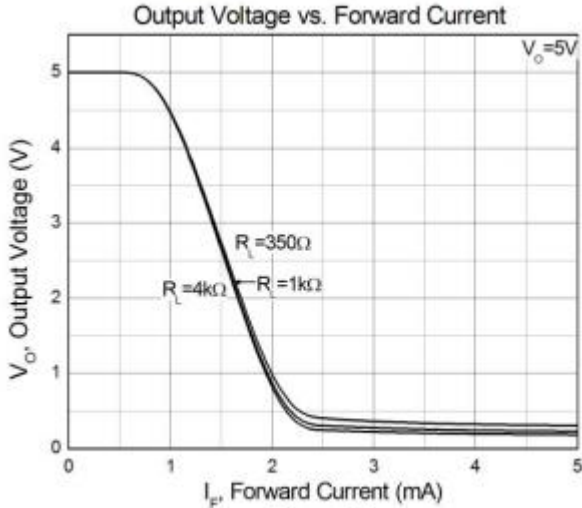


Figure 11

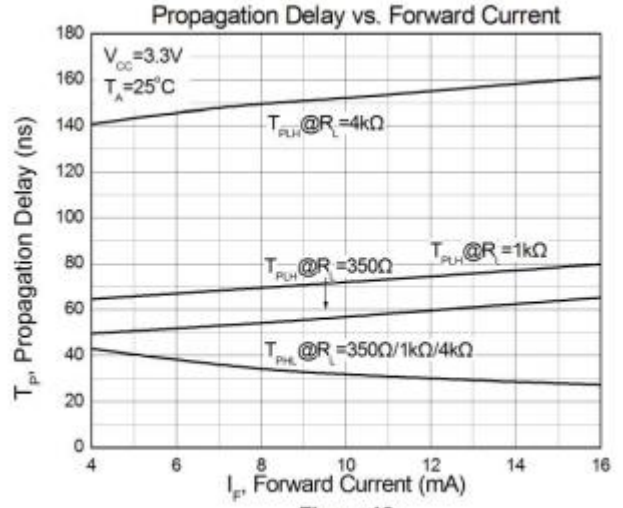


Figure 12

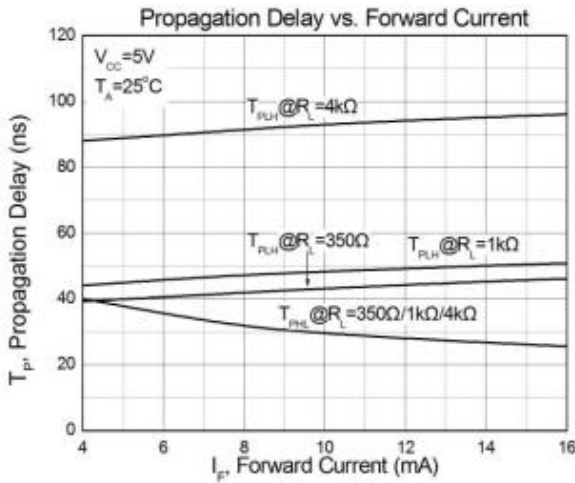


Figure 13

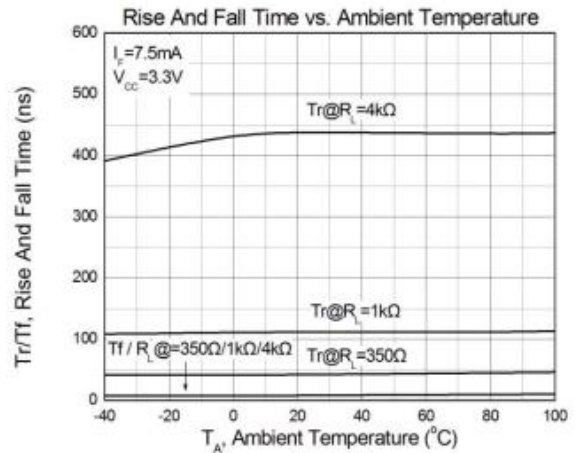


Figure 14

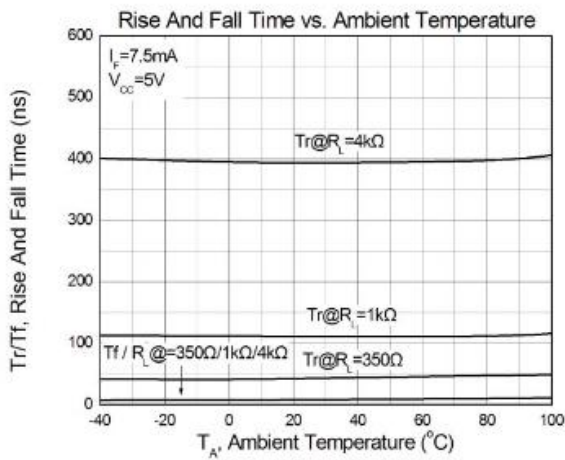


Figure 15

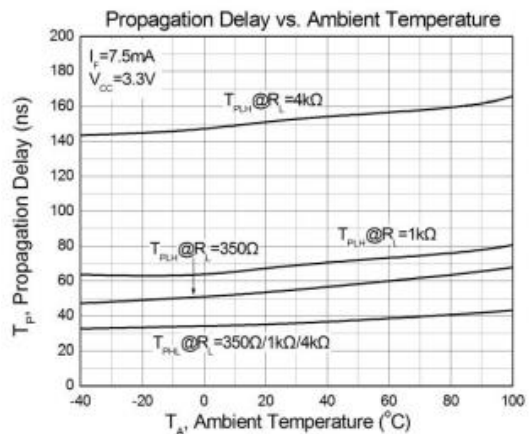
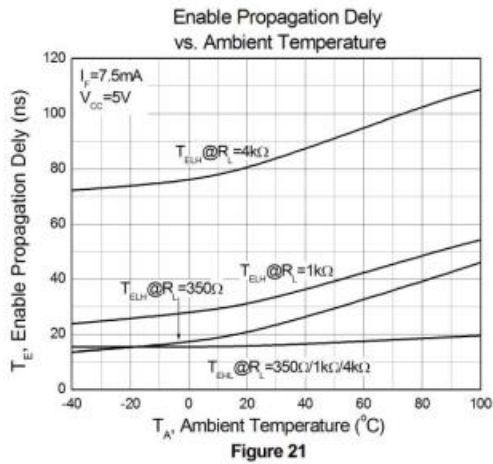
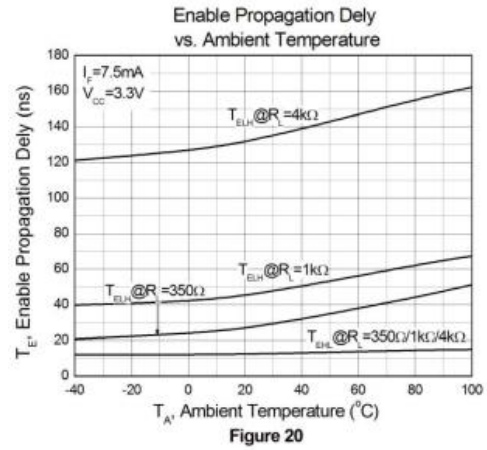
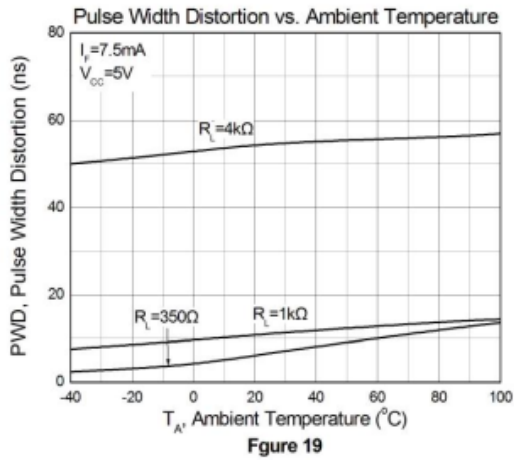
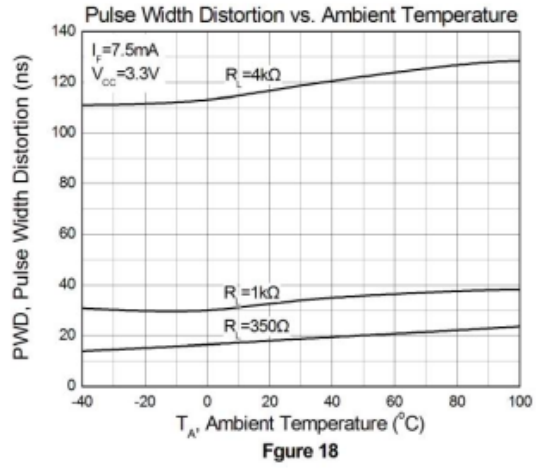
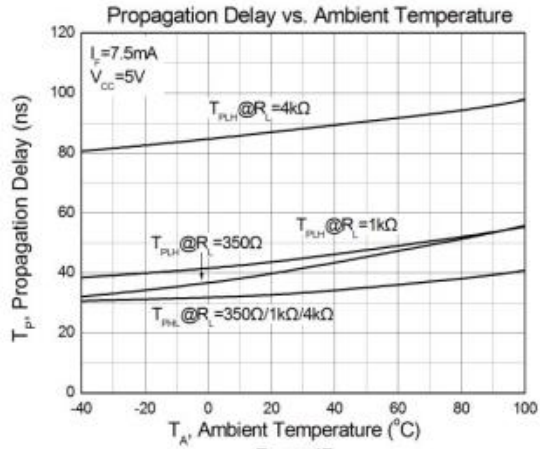
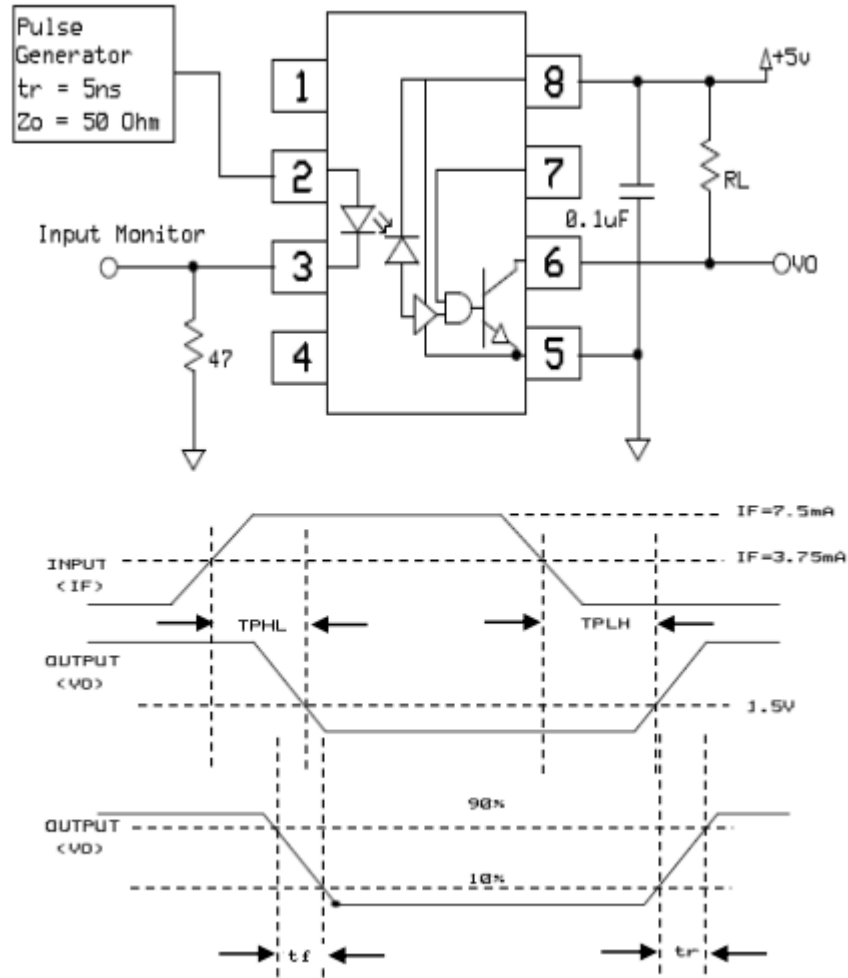


Figure 16

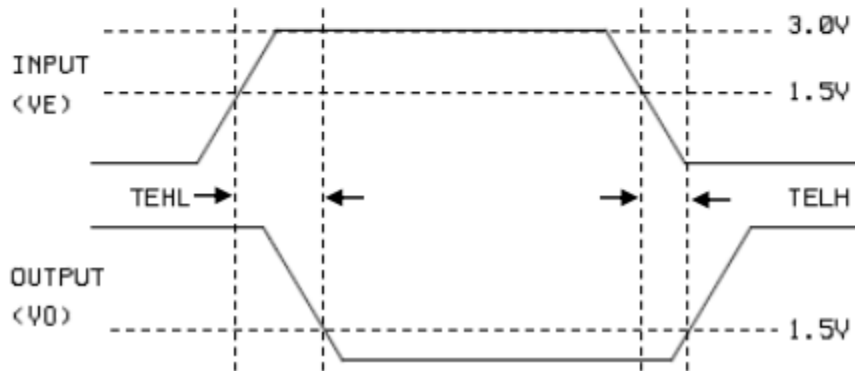
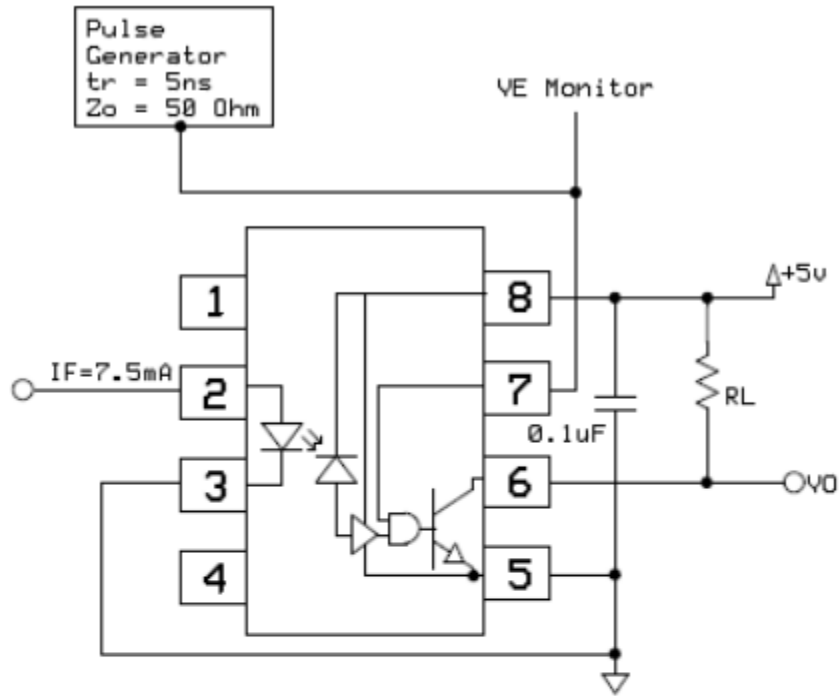


Test Circuits

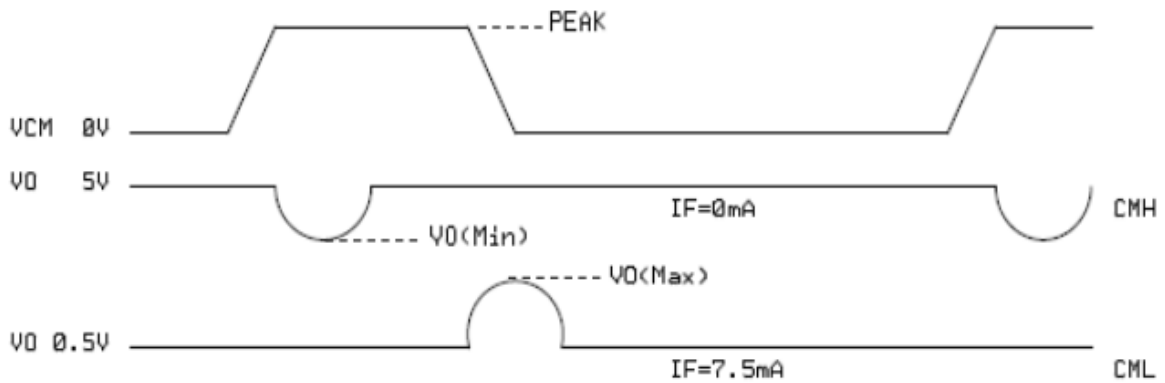
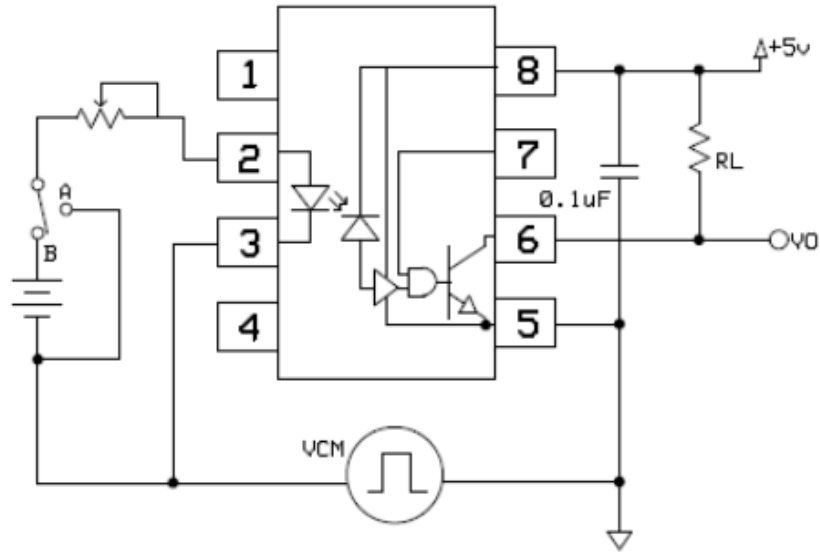
Switching Time Test Circuit



Enable Switching Time Test Circuit



CMR Test Circuit



Solder Profile & Footprint

Wave soldering Profile

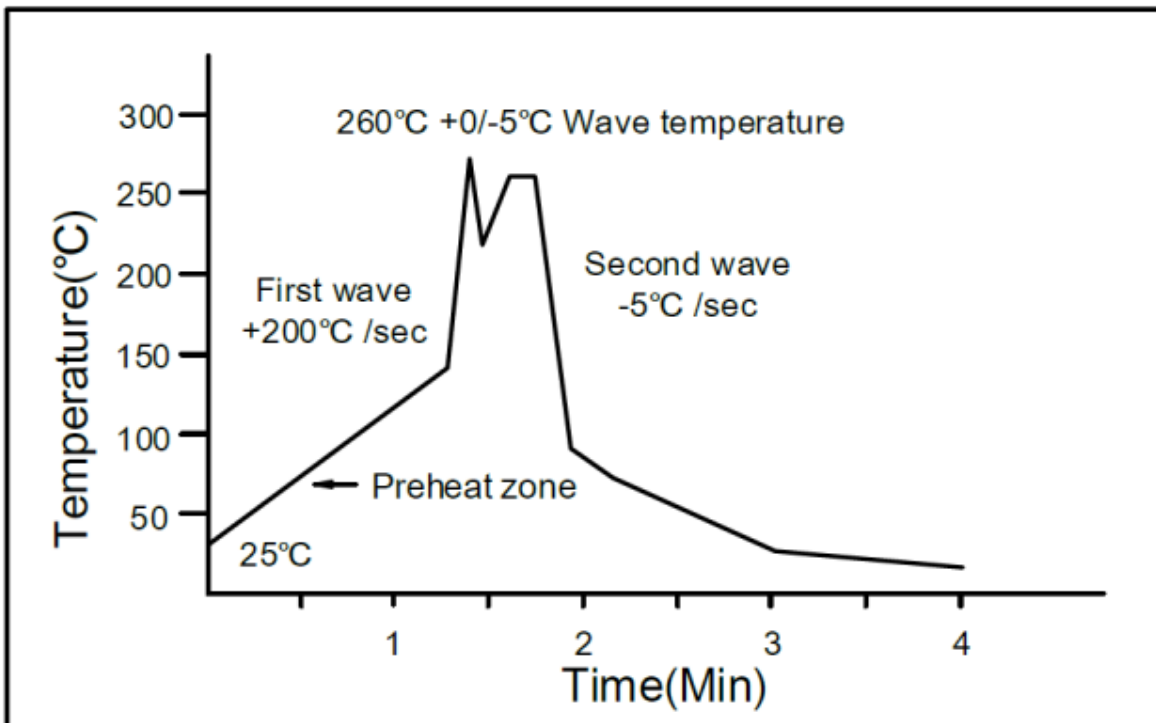
One time soldering is recommended within the condition of temperature.

Temperature: $260 \pm 5^\circ\text{C}$.

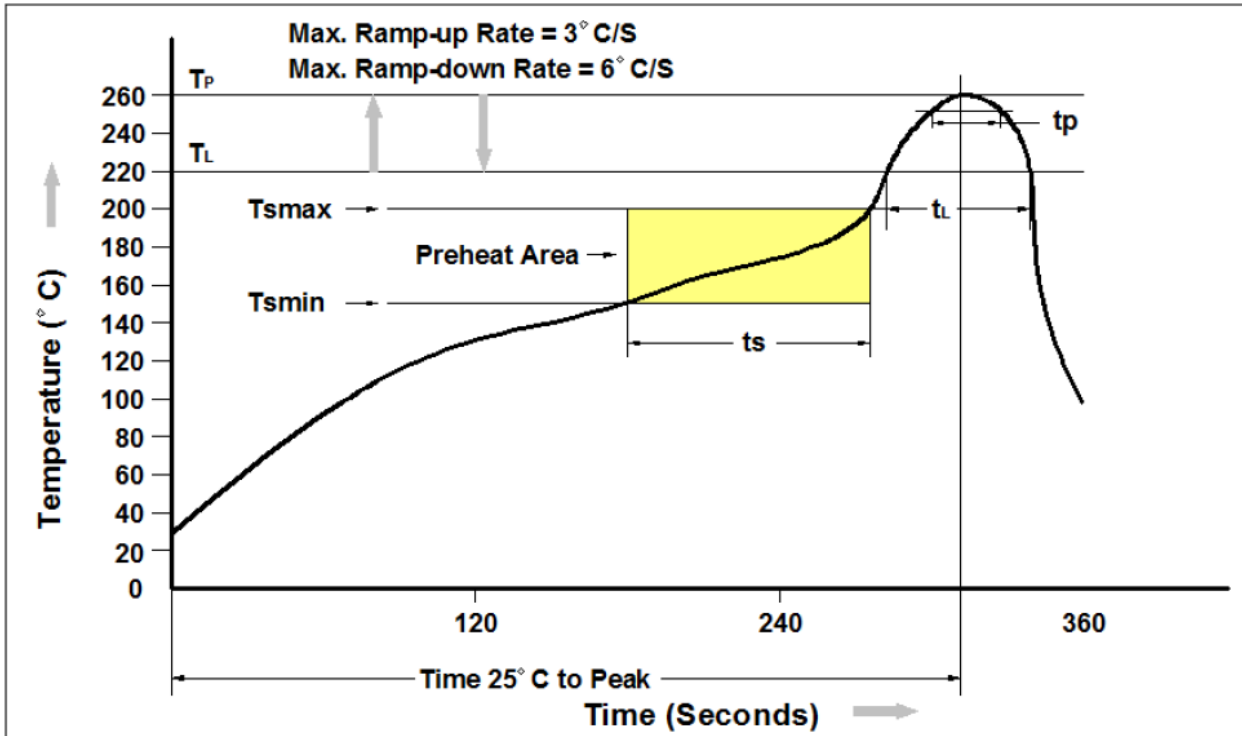
Time: 10 sec.

Preheat temperature: 25 to 140°C .

Preheat time: 30 to 80 sec.

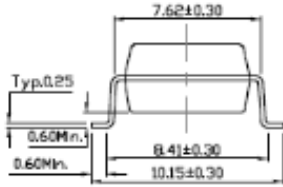


Reflow Profile

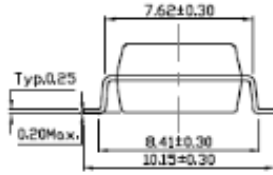


Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	150°C
Temperature Max. (T _{smax})	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

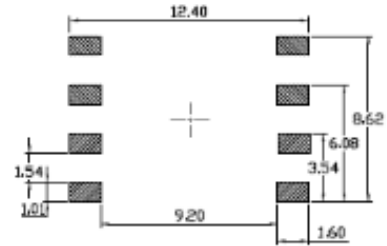
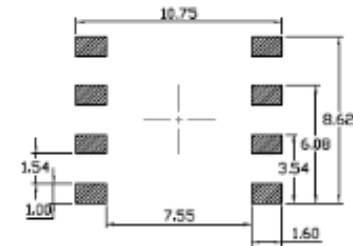
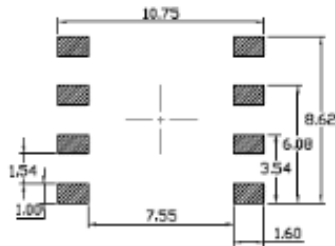
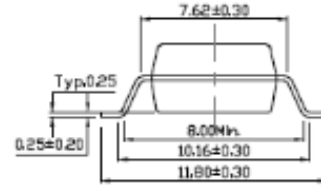
S Type



SL Type



SLM Type

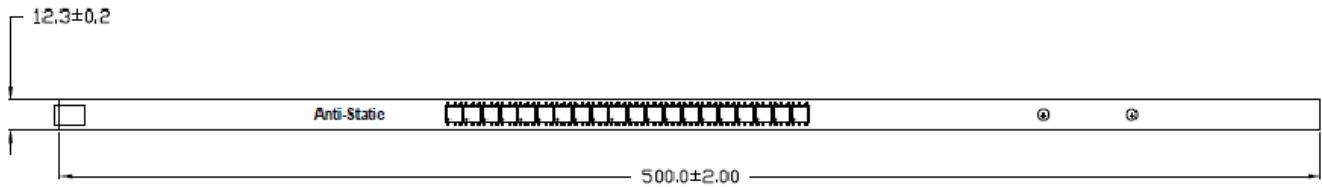


Recommended Solder Footprint for SMD Leadform

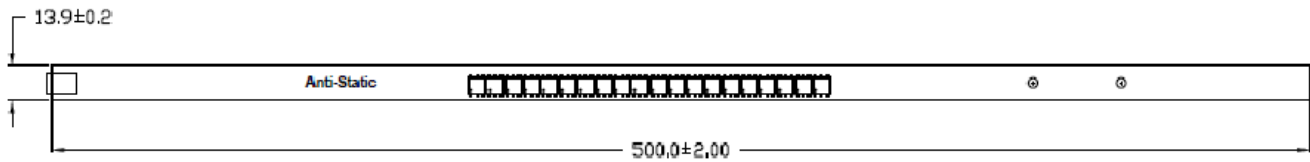
Units: mm

Packing & Labeling Tube Option

Standard DIP

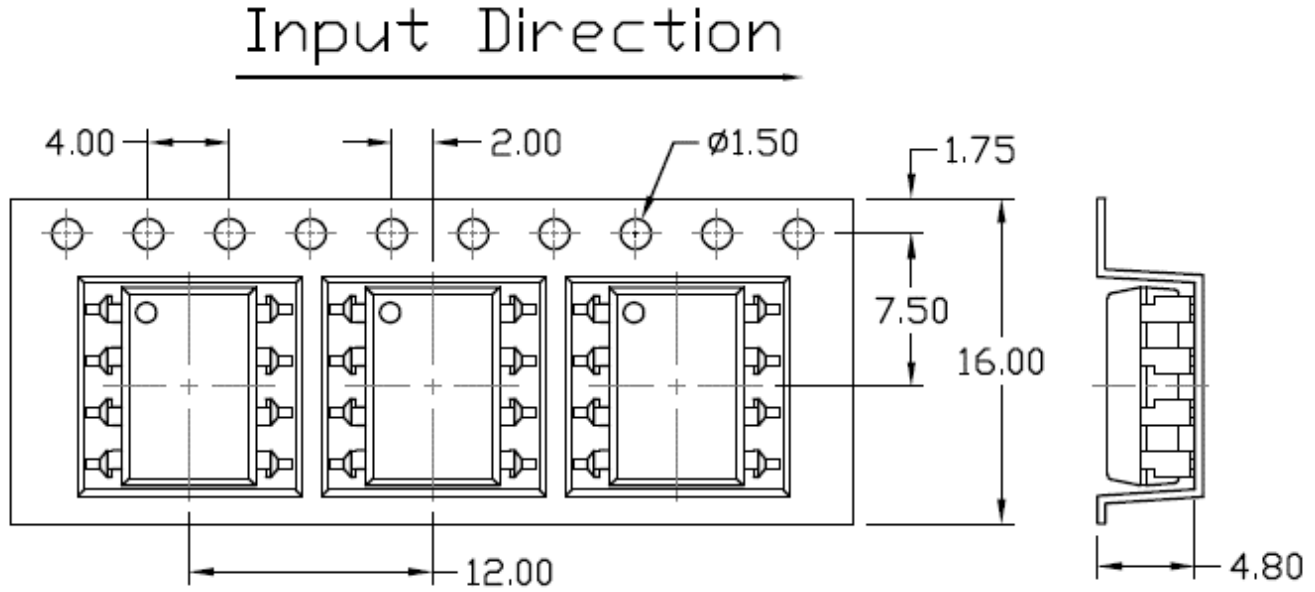


Tube Option M Type

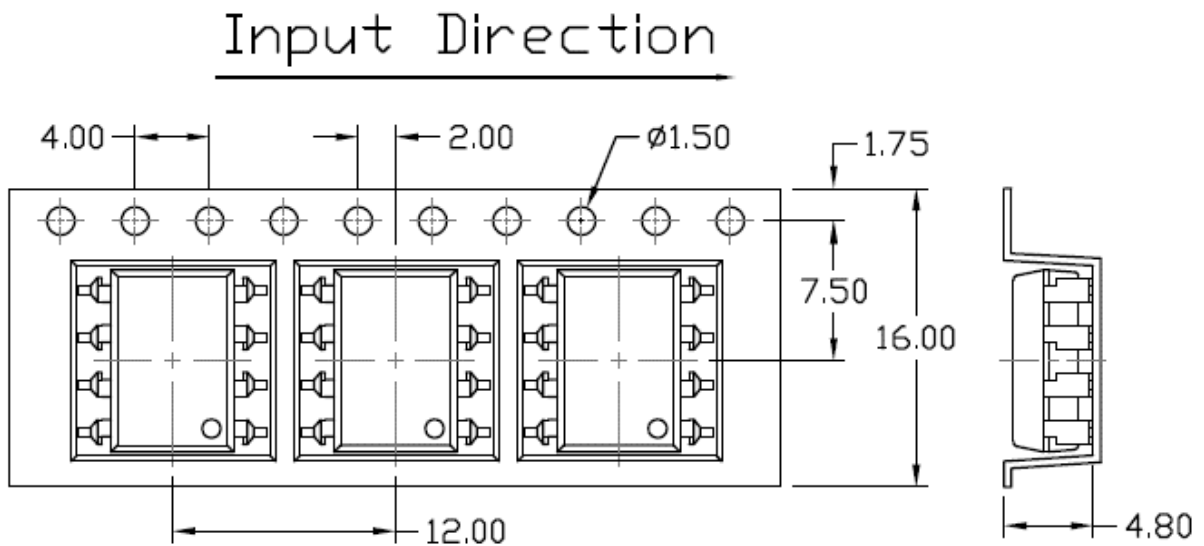


Tape Dimension for SMD:

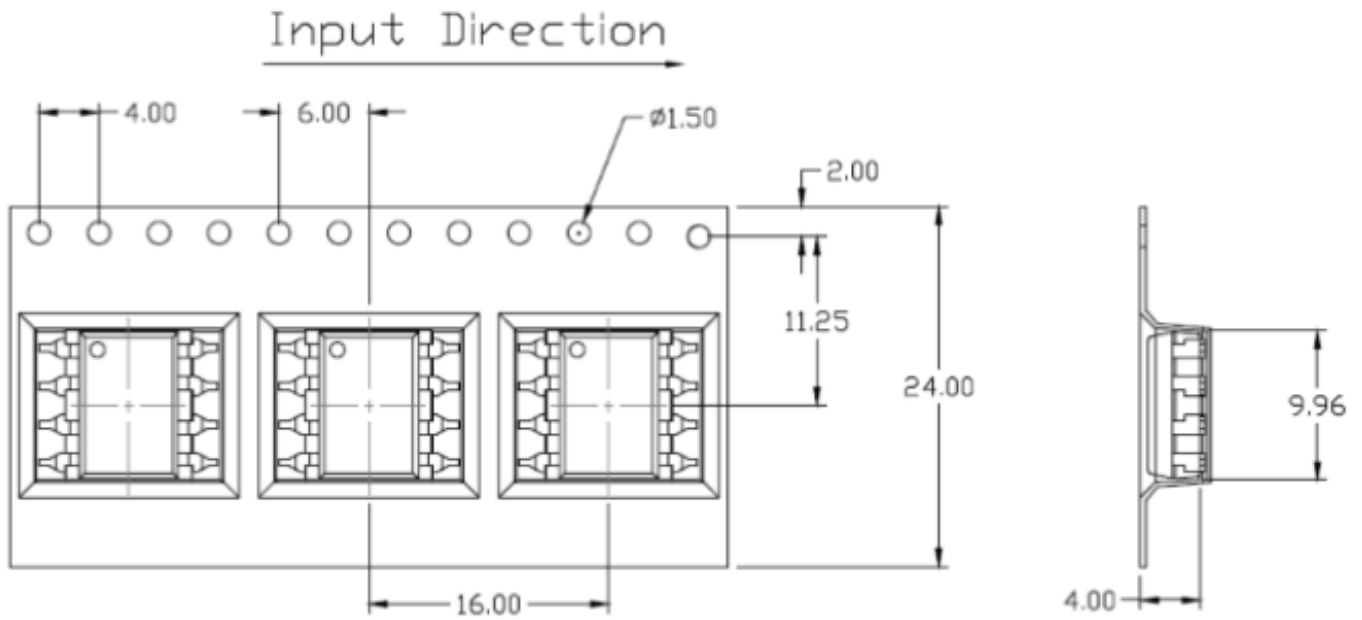
Option ST1 & SLT1



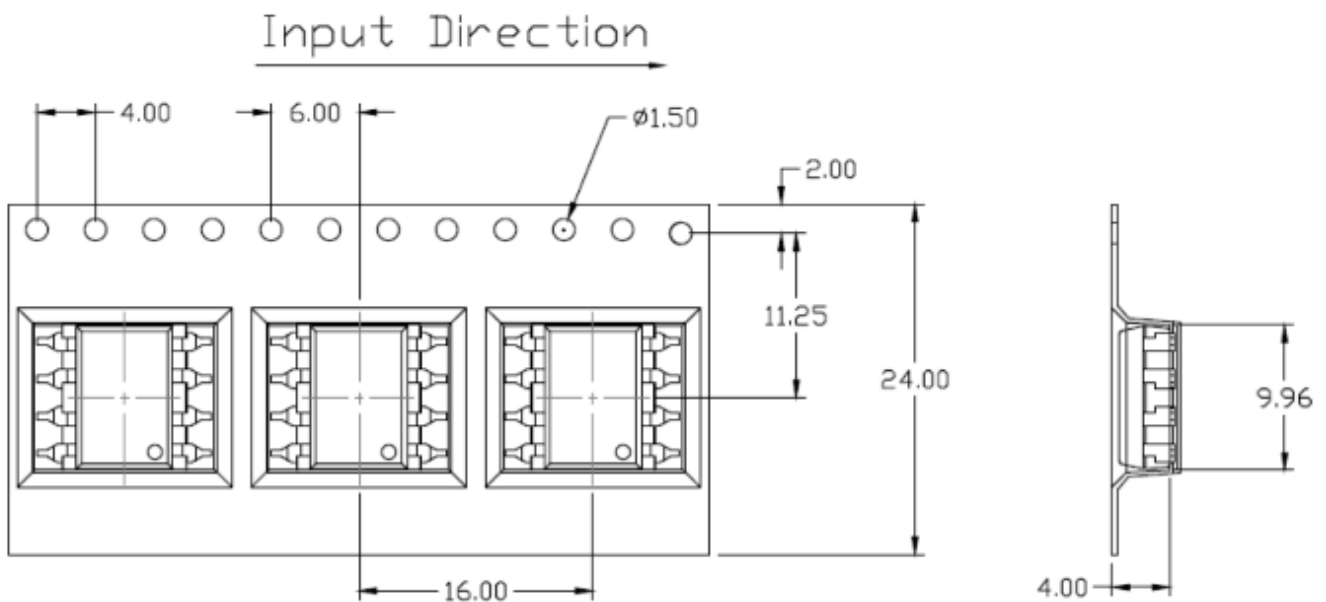
Option ST2 & SLT2



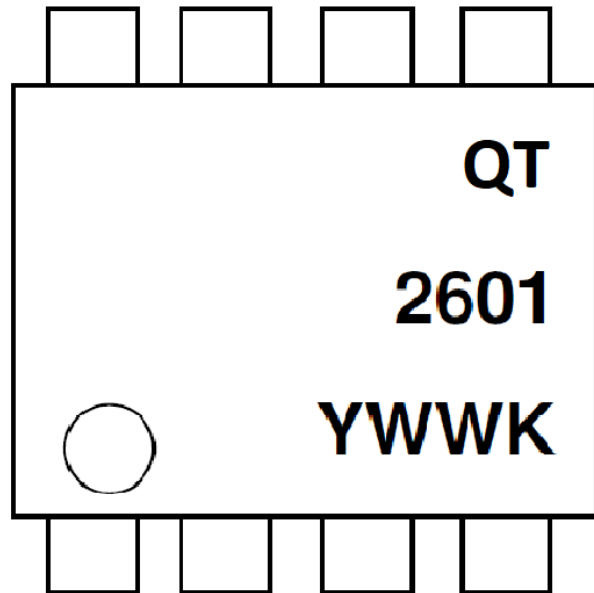
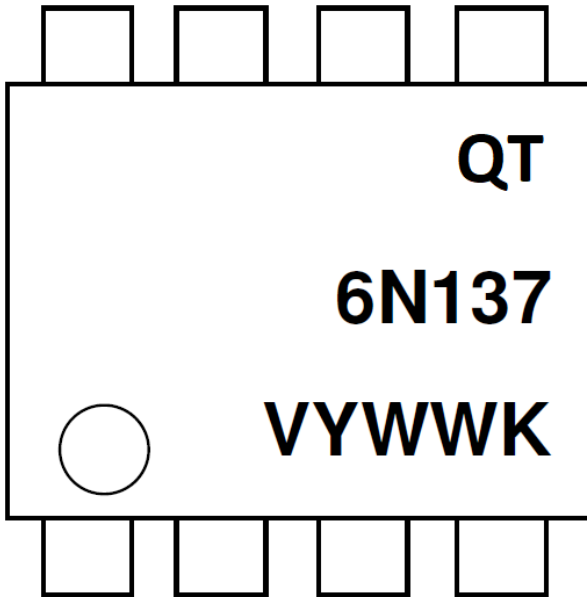
Option SLMT1



Option SLMT2



Dimension in mm

Device Marking

QT = QT-Brightek Corporation
6N137 or 2601 = part number
Y = Year
WW = Week
V = VDE Option
K = Manufacturing code

Ordering Information

6N137VYZ or QT2601VYZ

V = VDE option (V or None)

Y = Lead form option (S, SL, M, SLM or none)

Z=Tape and reel option (T1 or T2)

Option	Description	Quantity
None	Standard 8-Pin DIP	40 Units/Tube
M	Gullwing	40 Units/Tube
ST1	Surface Mount Lead Forming – with Option 1 Taping	1000 pcs/ reel
ST2	Surface Mount Lead Forming – with Option 2 Taping	1000 pcs/ reel
SLT1	SMD (Low Profile) Lead Forming – with Option 1 Taping	1000 pcs/ reel
SLT2	SMD (Low Profile) Lead Forming – with Option 2 Taping	1000 pcs/ reel
SLT1	SMD (Low Profile) Lead Forming – with Option 1 Taping	1000 pcs/ reel
SLT2	SMD (Low Profile) Lead Forming – with Option 2 Taping	1000 pcs/ reel



Revision History

Description:	Revision #	Revision Date
Initial release of 6N137_QT2601	1.0	02/12/2018
Update drawing and spec	1.1	03/26/2024

Disclaimer

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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.